

SPECIFICATION:

Please amend the specification as follows:

On page 1 lines 1 and 2, please amend the title of the invention as follows:

**METHOD FOR MANUFACTURING A MAGNETIC WRITE HEAD**  
**HAVING A NOVEL METAL WRITE**  
**GAP STRUCTURE FOR AN INDUCTIVE WRITE HEAD**

On page 20, lines 1 and 2, please amend the Title of the Invention as follows:

**METHOD FOR MANUFACTURING A MAGNETIC WRITE HEAD**  
**HAVING A NOVEL METAL WRITE**  
**GAP STRUCTURE FOR AN INDUCTIVE WRITE HEAD**

On page 20, please amend the Abstract as follows:

A method for manufacturing an inductive write head having a metal write gap layer. The method reduces the number of necessary process steps and avoids corrosion of other write head elements such as magnetic back gap. A magnetic write head having a metal, non-magnetic write gap that extends only partially to the magnetic back gap, the remainder of the distance between the pole tip and the back gap being a magnetic material. The elimination of the seed layer reduces the amount of milling required to perform the desired notching needed to form a self aligned pedestal on the first pole and voids electrolytic corrosion of the back gap during plating.

Please amend the paragraph beginning on page 12, ling 22 as follows:

Then, with reference to Fig. 10 an ion mill 1002 can be performed to remove selected portions of the write gap material layer 806 that are not covered by the photoresist mask. Thereafter, with reference to Fig. 11, with the photoresist mask still in place, a layer of magnetic material 1102, such as NiFe is deposited. The layer of magnetic material 1102 is preferably about the same thickness as the write gap material layer 806, but can have a thickness plus or minus 50% that of the write gap material layer 806. The magnetic layer 1102 can be deposited by sputter deposition. With reference to Fig. 12, the photoresist mask 902 can be removed and the second pole 712 can be formed by ~~electroplating~~ electroplating. It will be appreciated that, when the second pole 712 is being electroplated there is very little metal write gap material available and the majority of the surface area is covered by magnetic material 714. This virtually eliminates the corrosion problem experienced by the method described with reference to Figs. 3-6.